

H1170

特性/Features

Tg \geq 170 $^{\circ}$ C (DSC)
 优良耐CAF性 Excellent Anti-CAF resistance
 优良的通孔可靠性 Excellent T/H reliability
 低Z轴热膨胀系数 Low Z-CTE 2.9%
 优异的耐热性Td =347 $^{\circ}$ C, T288=30min
 High thermal performance Td =347 $^{\circ}$ C, T288=30min
 优异的尺寸稳定性 Excellent in dimension stability

应用领域/Applications

适合于高多层PCB、计算机及外围设备、通讯设备、汽车电子。
 Suitable for high-count layer PCB, computer, communication equipment, automotive electronics.

主要特性/General properties

检测项目 Item	单位 Unit	检测条件 Test Condition	规范值 Spec	典型值 Typical Value	
玻璃化转变温度/Tg	$^{\circ}$ C	DSC	\geq 170	182	
剥离强度/1oz Peel Strength	N/mm	288 $^{\circ}$ C, 10S	\geq 1.05	1.41	
热应力/Thermal stress	S	288 $^{\circ}$ C, solder dip	$>$ 10	180 ^s No delamination	
弯曲强度/Flexural Strength	N/mm ²	经向 LW 纬向 CW	\geq 415 \geq 345	570 465	
燃烧性/Flammability	—	E 24/125	UL94V-0	V-0	
表面电阻/Surface Resistivity	M Ω	After moisture E 24/125	\geq 1.0 \times 10 ⁴ \geq 1.0 \times 10 ³	9.8 \times 10 ⁷ 5.3 \times 10 ⁶	
体积电阻/Volume Resistivity	M Ω ·cm	After moisture E 24/125	\geq 1.0 \times 10 ⁸ \geq 1.0 \times 10 ³	3.21 \times 10 ⁸ 6.9 \times 10 ⁶	
介电常数/Dielectric Constant	—	1 MHz C 24/23/50	\leq 5.4	4.7	
介质损耗角正切/Loss Tangent	—	1 MHz C 24/23/50	\leq 0.035	0.016	
耐电弧/Arc Resistance	S	D48/50+D0.5/23	\geq 60	122	
击穿电压/Dielectric Breakdown	KV	D48/50+D0.5/23	\geq 40	58	
吸水率/Moisture Absorption	%	D24/23	\leq 0.35	0.01	
热分解温度/Td	$^{\circ}$ C	Weight Loss 5%	\geq 340	357	
CTE Z-axis	Alpha 1	ppm / $^{\circ}$ C	TMA	\leq 60	45
	Alpha 2	ppm / $^{\circ}$ C		\leq 300	270
	50 - 260 $^{\circ}$ C	%		\leq 3.0	2.9
T288	min	TMA	\geq 15	30	
T300	min	TMA	\geq 2	5	
相比漏电起痕指数/CTI	V	IEC-60112	175~250	200	

Specimen Thickness: 1.6mm; Specification sheet: IPC-4101D/126, is for your reference only
 Explanation: C: Humidity conditioning; D: Immersion conditioning in distilled water;
 E: Temperature conditioning;

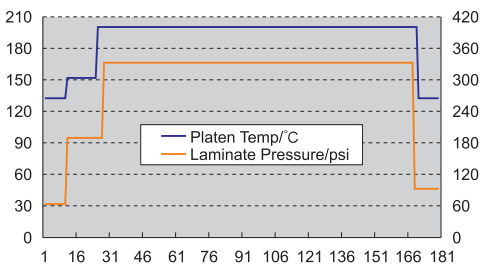
半固化片介绍-H1170P

Prepreg instruction

H1170P (UV Prepreg):

Prepreg Type	Resin Content(%)		压合厚度 / Cured Thickness			
	含量R/C(%)	公差Tolerance	Nominal		Range(±)mil	
	%	±	mm	mil	mm	mil
7628HRC	52	2	0.234	9.21	0.022	0.85
	50	2	0.223	8.78	0.022	0.85
	48	2	0.212	8.35	0.020	0.8
7628	45	2	0.197	7.76	0.019	0.75
	43	2	0.188	7.40	0.018	0.7
1506	48	2	0.166	6.54	0.017	0.65
	45	2	0.155	6.10	0.015	0.6
2116	58	2	0.138	5.43	0.014	0.55
	57	2	0.136	5.35	0.013	0.5
	55	2	0.127	5.00	0.013	0.5
	53	2	0.12	4.72	0.011	0.45
	50	2	0.111	4.37	0.011	0.45
1080	68	2	0.087	3.43	0.008	0.3
	65	2	0.077	3.03	0.008	0.3
	63	2	0.074	2.91	0.008	0.3

建议压制程式：Suggest cycle



Heat-up rate: 1.5~2.5°C/min (80~140°C)

Curing time: >80min (>190°C)

The hot pressing parameters is for your reference only, please turn to Zhejiang Huazheng New Material.Co.,Ltd for detailed information.

储存条件：

温度≤23°C、湿度≤50%，保存时间3个月；
温度≤5°C、密封条件下，保存时间6个月。

Storage Condition:

T≤23°C & ≤50%RH, Within 3 months;
T≤5°C Within 6 months (seal condition)

在上述要求内，我司可立即安排PP送样；
若有特殊要求，由供需双方商定。

Follow above condition, our company will arrange sample immediately. We can discuss if you have any special requirement.